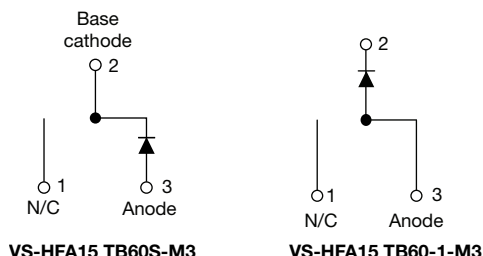
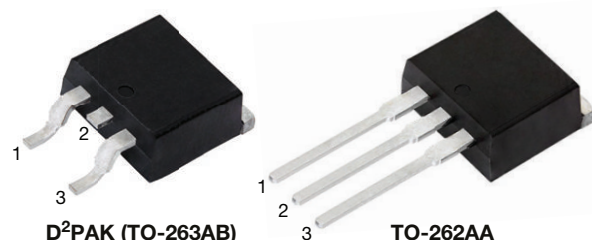


# HEXFRED®, Ultrafast Soft Recovery Diode, 15 A



## FEATURES

- Ultrafast and ultrasoft recovery
- Very low  $I_{RRM}$  and  $Q_{rr}$
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
FREE

## BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

## DESCRIPTION

VS-HFA15TB60S, VS-HFA15TB60-1 is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A continuous current, the VS-HFA15TB60S, VS-HFA15TB60-1 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to “snap-off” during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA15TB60S, VS-HFA15TB60-1 is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	15 A
$V_R$	600 V
$V_F$ at $I_F$	1.2 V
$t_{rr}$ (typ.)	23 ns
$T_J$ max.	150 °C
Package	D <sup>2</sup> PAK (TO-263AB), TO-262AA
Circuit configuration	Single

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		600	V
Maximum continuous forward current	$I_F$	$T_C = 100\text{ °C}$	15	A
Single pulse forward current	$I_{FSM}$		150	
Maximum repetitive forward current	$I_{FRM}$		60	
Maximum power dissipation	$P_D$	$T_C = 25\text{ °C}$	74	W
		$T_C = 100\text{ °C}$	29	
Operating junction and storage temperature range	$T_J, T_{Stg}$		-55 to +150	°C

**ELECTRICAL SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	$V_{BR}$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Maximum forward voltage	$V_{FM}$	$I_F = 15\text{ A}$	-	1.3	1.7	
		$I_F = 30\text{ A}$	-	1.5	2.0	
		$I_F = 15\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$	-	1.2	1.6	
Maximum reverse leakage current	$I_{RM}$	$V_R = V_R$ rated	-	1.0	10	$\mu\text{A}$
		$T_J = 125\text{ }^{\circ}\text{C}, V_R = 0.8 \times V_R$ rated	-	400	1000	
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	25	50	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5	$t_{rr}$	$I_F = 1.0\text{ A}, dI_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$	-	23	-	ns
	$t_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	50	60	
	$t_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	105	120	
Peak recovery current See fig. 6	$I_{RRM1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	4.5	6.0	A
	$I_{RRM2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	6.5	10	
Reverse recovery charge See fig. 7	$Q_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	84	180	nC
	$Q_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$	-	241	600	
Peak rate of fall of recovery current during $t_b$ See fig. 8	$dI_{(rec)M}/dt1$	$T_J = 25\text{ }^{\circ}\text{C}$	-	188	-	A/ $\mu\text{s}$
	$dI_{(rec)M}/dt2$	$T_J = 125\text{ }^{\circ}\text{C}$	-	160	-	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	$T_{lead}$	0.063" from case (1.6 mm) for 10 s	-	-	300	$^{\circ}\text{C}$
Thermal resistance, junction-to-case	$R_{thJC}$		-	-	1.7	K/W
Thermal resistance, junction-to-ambient	$R_{thJA}$	Typical socket mount	-	-	80	
Thermal resistance, case-to-heatsink	$R_{thCS}$	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Marking device		Case style D <sup>2</sup> PAK (TO-263AB)	HFA15TB60S			
		Case style TO-262AA	HFA15TB60-1			

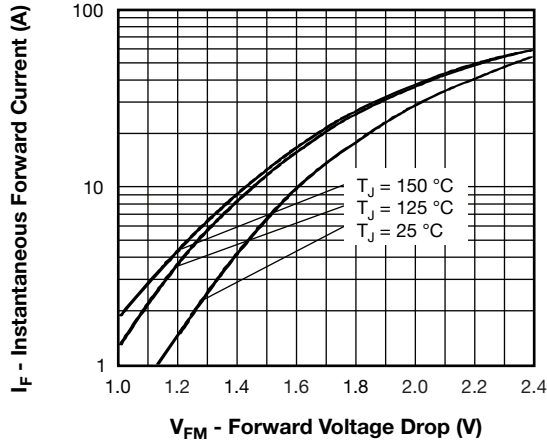


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

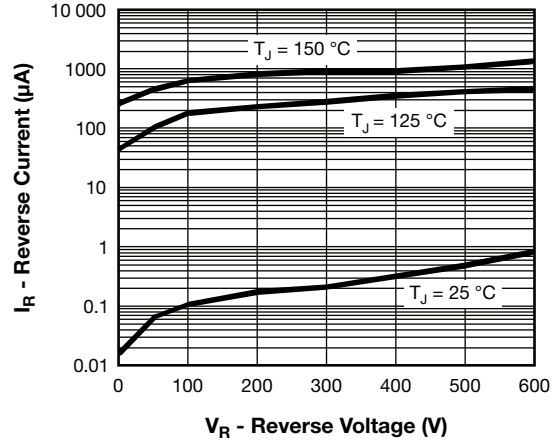


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

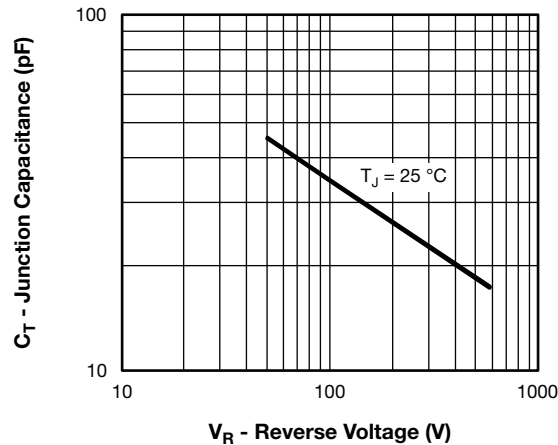


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

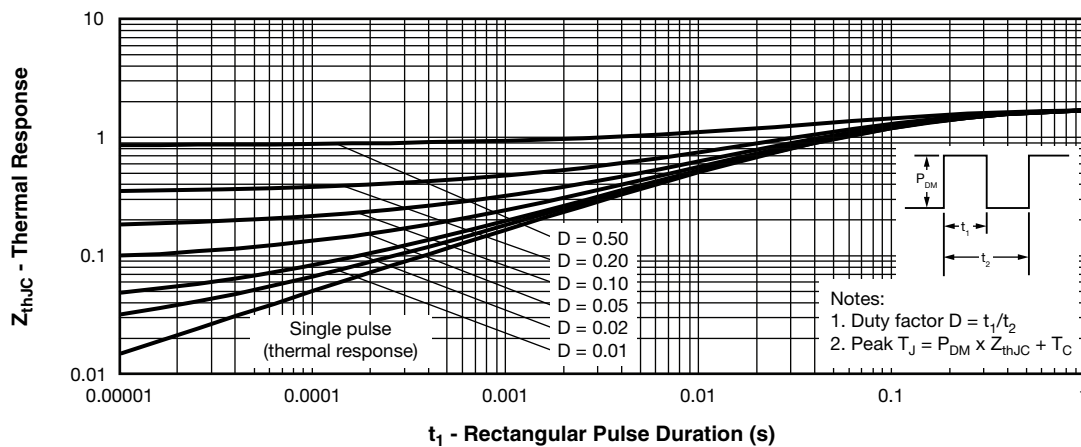


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

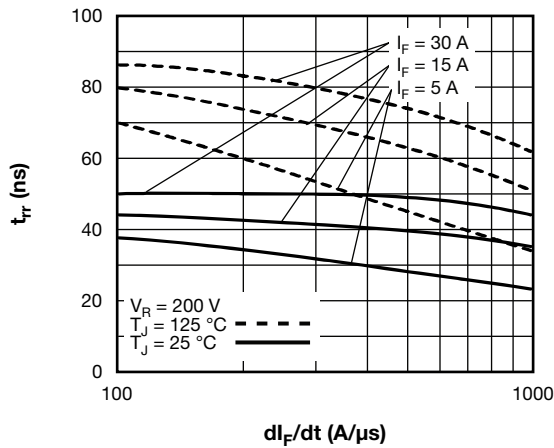


Fig. 5 - Typical Reverse Recovery Time vs.  $dI_F/dt$

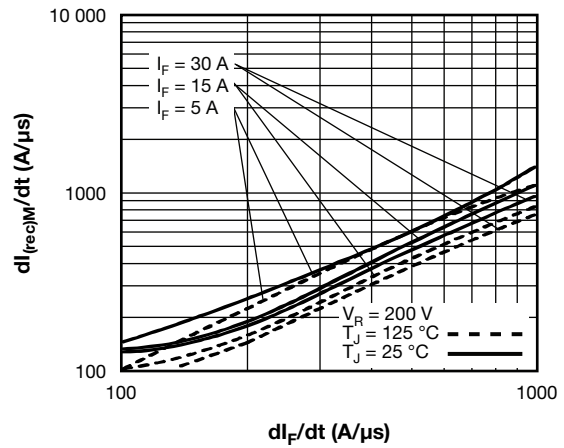


Fig. 8 - Typical  $dI_{(rec)M}/dt$  vs.  $dI_F/dt$

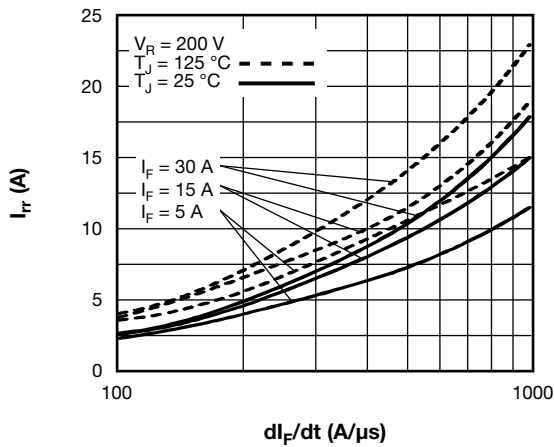


Fig. 6 - Typical Recovery Current vs.  $dI_F/dt$

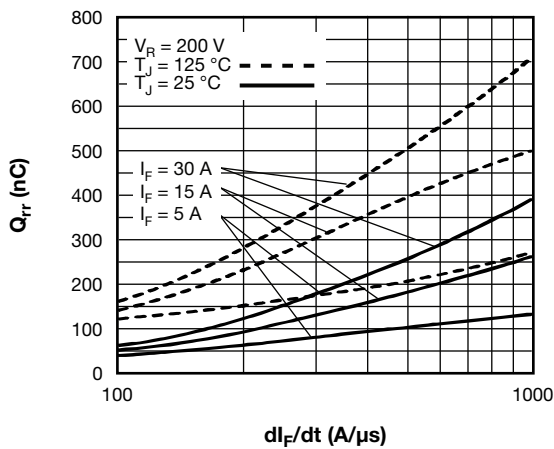


Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$

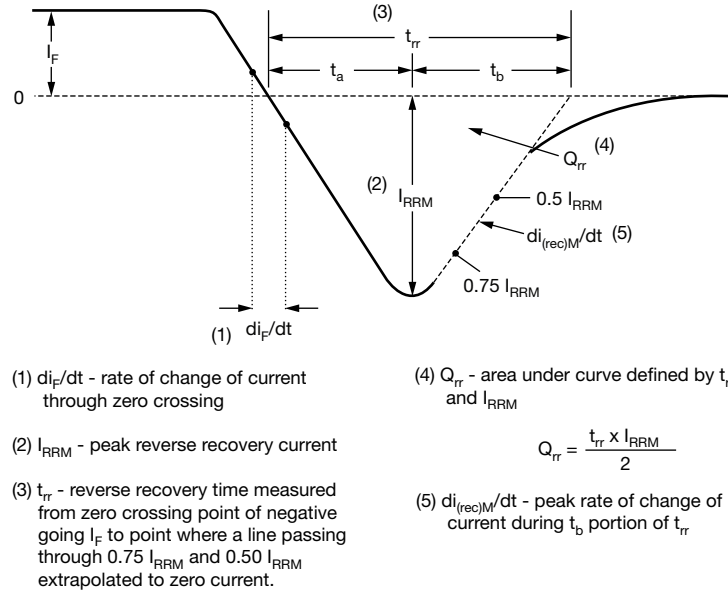


Fig. 9 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

Device code	<b>VS-</b>	<b>HF</b>	<b>A</b>	<b>15</b>	<b>TB</b>	<b>60</b>	<b>S</b>	<b>L</b>	<b>-M3</b>
	1	2	3	4	5	6	7	8	9

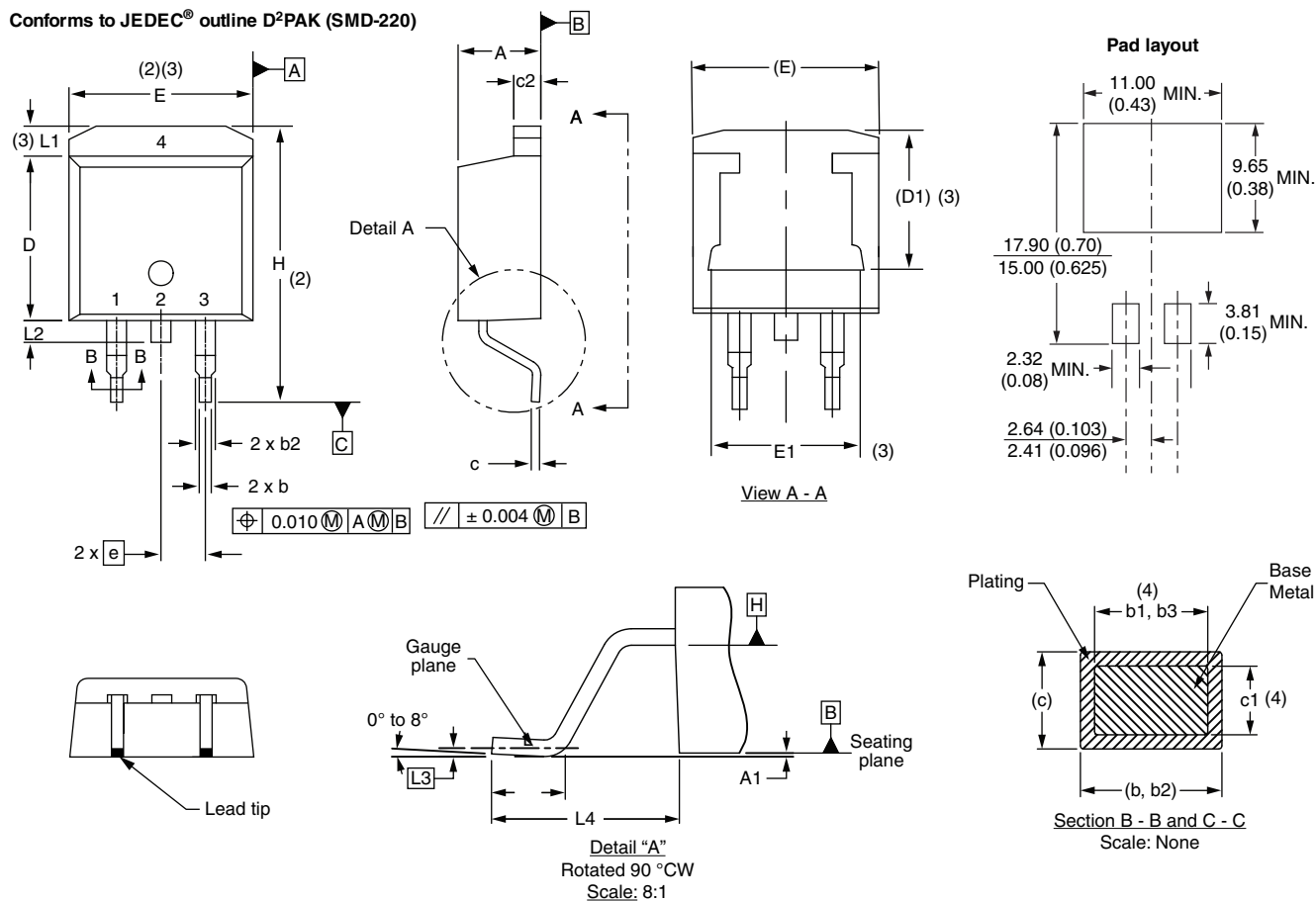
- 1 - Vishay Semiconductors product
- 2 - HEXFRED® family
- 3 - Electron irradiated
- 4 - Current rating (15 = 15 A)
- 5 - Package:  
TB = TO-220
- 6 - Voltage rating (60 = 600 V)
- 7 - • S = D<sup>2</sup>PAK (TO-263AB)  
• -1 = TO-262AA
- 8 - • None = tube (50 pieces)  
• L = tape and reel (left oriented, for D<sup>2</sup>PAK (TO-263AB) package )  
• R = tape and reel (right oriented, for D<sup>2</sup>PAK (TO-263AB) package)
- 9 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

### ORDERING INFORMATION (Example)

PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-HFA15TB60S-M3	50	Antistatic plastic tube
VS-HFA15TB60SL-M3	800	13" diameter reel
VS-HFA15TB60SR-M3	800	13" diameter reel
VS-HFA15TB60-1-M3	50	Antistatic plastic tube

## LINKS TO RELATED DOCUMENTS

Dimensions	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?96164">www.vishay.com/doc?96164</a>
	TO-262AA	<a href="http://www.vishay.com/doc?96165">www.vishay.com/doc?96165</a>
Part marking information	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a>
	TO-262AA	<a href="http://www.vishay.com/doc?95443">www.vishay.com/doc?95443</a>
Packaging information		<a href="http://www.vishay.com/doc?96424">www.vishay.com/doc?96424</a>
SPICE model		<a href="http://www.vishay.com/doc?95357">www.vishay.com/doc?95357</a>

**D<sup>2</sup>PAK****DIMENSIONS** in millimeters and inchesConforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

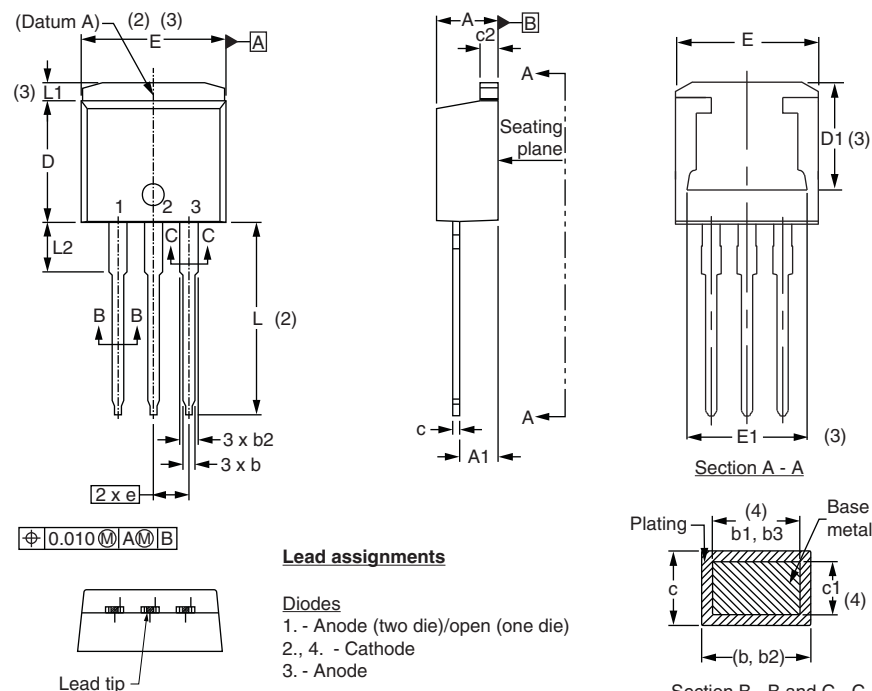
**Notes**

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

### TO-262AA

**DIMENSIONS** in millimeters and inches

Modified JEDEC® outline TO-262



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)





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